

	Hits	Search Text	DBs
24	0	((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide)) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same (plural or second))	US-PGPUB

	Hits	Search Text	DBs
25	0	((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide)) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB